

<b>Notification Number:</b>	20201014001	<b>Notification Date:</b>	Jan. 12, 2021
<b>Title:</b>	Datasheet for TMP175, TMP75		
<b>Customer Contact:</b>	<a href="#">Notification Manager</a>	<b>Dept:</b>	Quality Services
<b>Change Type:</b> Electrical Specification			

**Description of Change:**

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



**TMP175, TMP75**

SBOS288M – JANUARY 2004 – REVISED OCTOBER 2020

<b>Changes from Revision L (December 2015) to Revision M (October 2020)</b>	<b>Page</b>
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Changed Absolute maximum Supply voltage of TMP75 from 7 V to 6.5 V.....	5
• Added applicable pins to Input voltage specification.....	5
• Changed Absolute maximum Input Voltage of TMP75 on SCL, SDA, A0, and A1 pins from 7 V to 6.5 V.....	5
• Changed Absolute maximum of TMP75 A2 pin voltage from 7 V to (V+)+0.3.....	5
• Removed ESD Machine Model specification from TMP75.....	5
• Updated TMP75 D and DGK package Thermal Information.....	5
• Updated TMP175 D package Thermal Information.....	5
• Added register settings to Conversion time specification for clarity.....	6
• Changed minimum Data setup specification time from 10 ns to 20 ns.....	7
• Moved Timeout specification to I2C Interface Timing table.....	7
• Changed TMP75 Timeout specification minimum from 25 to 20.....	7
• Changed TMP75 Timeout specification maximum from 74 to 30.....	7
• Removed BYTE column from the <i>Configuration Register</i> table.....	18
• Changed TMP75 consecutive fault setting F[1:0] = 11 from 6 to 4 and F[1:0] = 10 from 4 to 3. ....	19
• Added behavior clarification when changing thermostat modes on TMP75.....	20
• Changed bypass capacitor recommendation from 0.1 μF to 0.01 μF.....	22
• Updated recommended pull-up resistor size to standard 4.7 kΩ .....	22
• Removed <i>Related Links</i> section.....	25
• Added <i>Receiving Notification of Documentation Updates</i> section.....	25

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP175, TMP75	SBOS288L	SBOS288M

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TMP75>

**Reason for Change:**

To accurately reflect device characteristics.

**Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):**

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

**Changes to product identification resulting from this notification:**

None.

**Product Affected:**

TMP75AID	TMP75AIDGKR	TMP75AIDGKT	TMP75AIDR
TMP75AIDG4	TMP75AIDGKRG4	TMP75AIDGKTG4	TMP75AIDRG4
TMP175AID	TMP175AIDGKR	TMP175AIDGKT	TMP175AIDGKTG4

TMP175AIDR			
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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